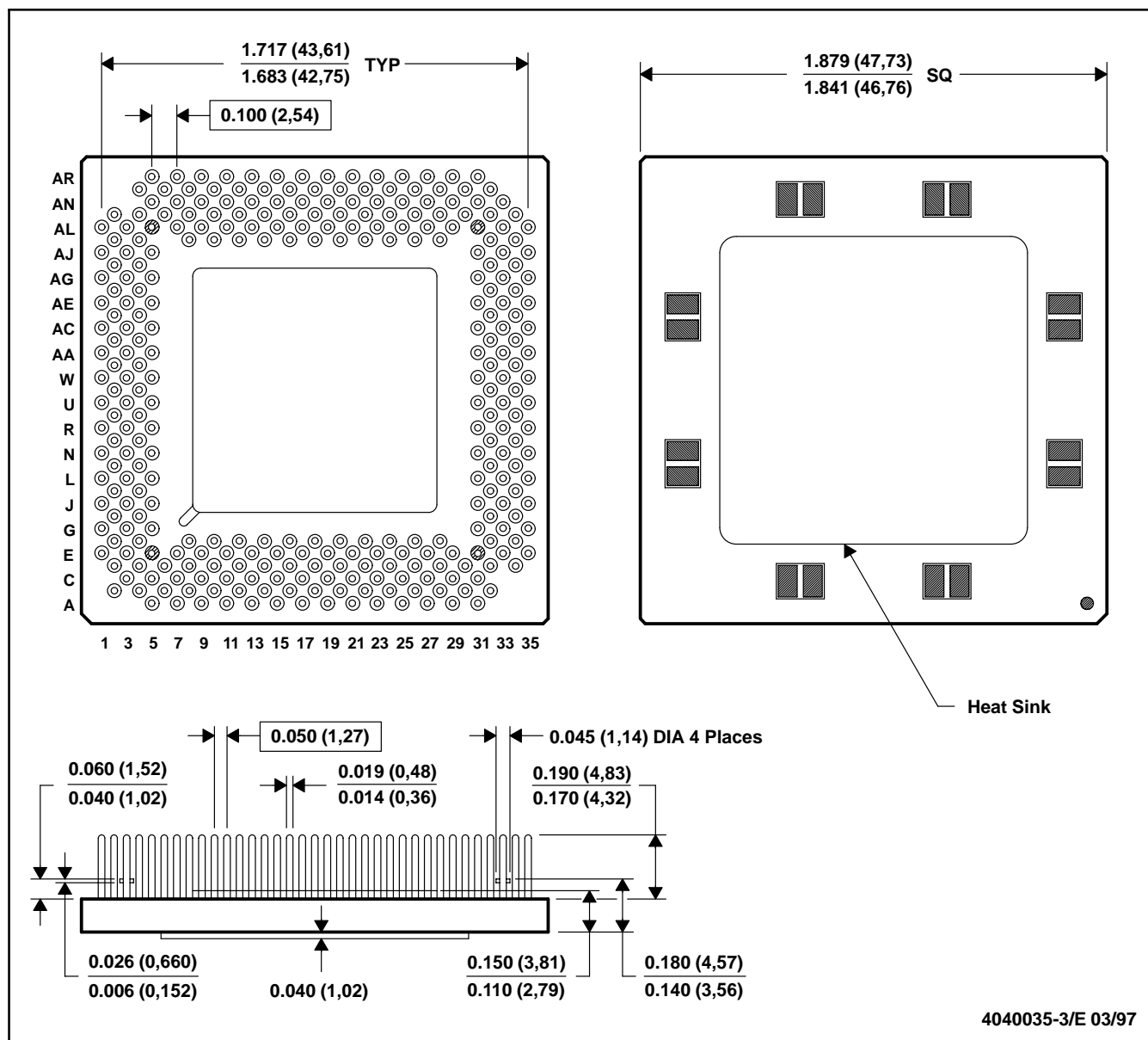


GF (S-CPGA-P305)

CERAMIC PIN GRID ARRAY



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Package thickness of 0.150 (3,81) / 0.110 (2,79) includes package body and lid, but does not include integral heat sink or attached features.

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